

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|---|------------------|
| 1 | 62 | half adj capacitor? | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:06 |
| 2 | 3 | (half adj capacitor?) same (chip? die?) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:07 |
| 4 | 1 | ((half adj capacitor?) same (chip? die?)) and @ad<19930624 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:09 |
| 5 | 34 | (half adj capacitor?) and @ad<19930624 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:26 |
| 6 | 9 | (half adj capacitor?) same (module chip substrate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:34 |
| 7 | 4 | ((half adj capacitor?) same (module chip substrate)) and @ad<19930624 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:39 |
| 8 | 31657 | (first) adj (module chip substrate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:38 |
| 9 | 0 | (half adj capacitor?) same (second) adj (module chip substrate) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:38 |
| 10 | 92 | (module? chip?) same capacitively adj coupl\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:39 |
| 11 | 35 | ((module? chip?) same capacitively adj coupl\$3) and @ad<19930624 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/03/03 17:40 |